

Manufacturing Info

MBOI

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Exceptions

PH4 ISPL (ATEC) (CU) MBOI Data

Search Files:

74VHC00MTCX-IPN


Search


MBOI Masters


ASY (850)MEF (4)TST (925)Open Compliance (832)

Search text is highlighted in RED 74VHC00MTCX-IPN

Manufacturing Bill of Information (MBOI)			
Part Number	74VHC00MTCX-IPN-ASY	Part Type	Assembly Part
Site Name Loc Cod	PH4 ISPL (ATEC) CU	File Name	PH4_74VHC00MTCX-IPN_74VHC00MTCX-IPN-ASY_ASY
Flags	Non Safe Launch Item No Global Hold Flag	Part Qual Target Market:	I Industrial
Part Version	5	Part Version Date-Time	2024-MAY-05 05:42:36 (GMT +7)

Orderable Part Section - OPN			
Part Number Desc	74VHC00MTCX-IPN Quad 2-Input NAND Gate	Market PN	74VHC00MTCX-IPN
Lifecycle Phase	Production	Part Class Desc	AA ASSEMBLED AND TESTED
Marketing Product Lifecycle	Follow Part Lifecycle	Part Sub Type	OPN
Part Release Status Desc	MC-M Mass Production	Part Usage	STD
Case Outline (CO)	948G 	PAL4 Code Desc	
Product Data Sheet			
ERP Resource Code - ASY Desc	F304 TSSOP14 AU SNGL HPBF	OPN Part Qual Target Market	I Industrial
Packing Configuration	TSSOP-14_948G_REEL_2500_FBQ5000	Eng Package Type	TSSOP-14

Assembly Part Section - ASY			
Part Number	74VHC00MTCX-IPN-ASY	Description	Quad 2-Input NAND Gate
Lifecycle Phase	Production	Part Usage	STD
Part Release Status Desc	MC-M Mass Production	Part Sub Type	ASY
PAL4 Code Desc		ERP Resource Code - ASY Desc	F304 TSSOP14 AU SNGL HPBF
Part Qual Target Market	I Industrial		
Case Outline (CO)	948G 	Package Type	TSSOP-14
ECAT Override		Actual Lead Count	14
Package Assembly Platform	SOSM - Small Outline Surface Mount	Assembly Baseline Spec	
Assembly Process Flow Spec		Assembly Spec(s) - Global	
Lot Processing Restrictions	Standard	Package Substrate Layout(s)	
ITAR Part Flag	N	Customs Configuration	8542.39.0001
Customs ECCN Code	EAR99	Customer Consigned Flag	N
Compressed?		Compressed Part Number	
Wettable Process Type		Wettable Flank Flag	
Site Notes			

BOM Components								
Alternate 002	Part Number	Part Sub Type	Line	Preference	Group	Qty	Description	Lifecycle Phase
Primary Die	74VHC00-XEC3026D-WDQ 	WDQ	001	01	0	1	Wafer 200	Production
	Die Size (X + Y W/Scribe Street): 617.2 x 617.2					PDPW : 74087		
Package Kit	N17608G030	PKT	002	01	0	1	PKGKIT TSSOP14 CU (PH4)	Production
	Piece Parts							
	1360100014	FRAME	010	01	0	1	LF TSSOP 14L JEDEC 4.4MM STAMPED PPF	Production
	13601510002	EPXY	020	01	0	1	DA HE QMI519 2.5CC/5CC	Production
	13601610001	WIRE	030	01	0	1	BW Au 0.8 MIL	Production
	1360191000	MOLD	040	01	0	1	MC HITACHI CEL800JF 13MMX5.3G	Production
BOI 67-Bonding Diagram	67AON20087G B	DOC	003	01	0	1	74VHC00x Series	Production



Standard Marking Flag			
PB Free Mark Character Flag			
Consolidated Mark Machine Std		Consolidated Mark Machine Custom	Line1: \$Y&Z&2&K Line2: V00 Line3: UNK Line4: UNK Line5: UNK

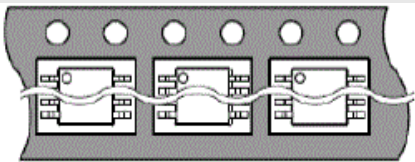
Marking Details Section

Date Code Type	S2		
Trace Code Legend - Front			
Trace Code Legend - Back			
Trace Code Spec	12MON45426G BD	Part Marking Source	
Part Marking Image/CAD Document		Marking Style Image Document	
Custom Logo Document		ON Logo Document	
Final Test Specification	48AON61241H O		

OPN Packing Section

PCQ Container Desc	REEL Tape and Reel	PCQ Quantity	2500
MPQ Container Desc	REEL Tape and Reel	MPQ Quantity	2500
Intermediate Full Box Container Type Intermediate Box Container Size Intermediate Full Box Container Quantity	 5000	Intermediate Full Bag Container Type Intermediate Bag Container Size Intermediate Full Bag Container Quantity	

Pin 1 Toward Upper Left



Labeling Section

MSL	1	MSL Temperature	260
Pb Free Leads Flag	Y	Halide Free Flag	Y
Pb Free Die Attach Flag	Y	Lead Finish Category (eCAT)	e4

Document Group Section


Document Num	Revision	Release Date	Title
12MON01117D	AC	15-Nov-23	Quality Assurance Inspection and Testing Sample Plan
12MON03769D	Y	04-Jul-22	External Visual Inspection Criteria
12MON45426G	BD	02-Feb-23	Mark Layout Instructions
12MON49004E	AD	14-Apr-23	Subcontractors Bar Code Labeling
12MRB17500B	FM	19-Sep-23	Finished Goods Packing and Long Term Storage Procedure
12MRM92695A	AE	27-Feb-24	Lot Combination Control Requirements for onsemi
48AON61241H	O	05-Feb-24	74VHCxx, 74LCXxx & 74LVXxx Series
67AON20087G	B	02-Feb-24	74VHC00x Series

BOM Links

Up/Down Direction	Site	Top Part	Link
Up	PH4	74VHC00MTCX-IPN	PH4_74VHC00MTCX-IPN_74VHC00MTCX-IPN-TST_TST.XML

Revision History

Rev	Rev Date	Details
5	2024-FEB-21 05:03:47	LIFECYCLE_PHASE CONFIRM_REQUIRED previous_value:Prototype;new_value:Production LIFECYCLE_PHASE CONFIRM_REQUIRED previous_value:Prototype;new_value:Production PART_REL_DATE_PROD UPDATE_FILE_AND_VERSION previous_value:NULL;new_value:20-FEB-24
4	2024-FEB-13 12:12:23	Deleted Component:67AON20162G Deleted Component:74VHC00-XBA30267-WDQ

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2	2024-JAN-23 15:04:50	LEAD_FINISH_CATEGORY_ECAT CONFIRM_REQUIRED previous_value:NULL;new_value:e4 MARK_STYLE_CONFIG_ID CONFIRM_REQUIRED previous_value:NULL;new_value:NO_STANDARD_MARKING_STYLE MARK_STYLE_SPEC UPDATE_FILE_AND_VERSION previous_value:NULL;new_value:ON Custom PB_FREE_DIE_ATTACH_FLG CONFIRM_REQUIRED previous_value:NULL;new_value:Y PB_FREE_IND_G_CD_IND UPDATE_FILE_AND_VERSION previous_value:NULL;new_value:None PB_FREE_LEADS_FLG CONFIRM_REQUIRED previous_value:NULL;new_value:Y PIN1_IND UPDATE_FILE_AND_VERSION previous_value:NULL;new_value:N/A POLARITY_IND UPDATE_FILE_AND_VERSION previous_value:NULL;new_value:NA STD_MARK_FLG UPDATE_FILE_AND_VERSION previous_value:Y;new_value:N
1	2024-JAN-18 00:03:51	Initial version

About onsemi

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Leadership

Corporate Fact Sheet

Quality and Reliability

Ecosystem Partners

Intellectual Property

Our History

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